



DGD2101

HIGH-SIDE AND LOW-SIDE GATE DRIVER IN SO-8 (Type TH)

Description

The DGD2101 is a high-voltage / high-speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a high-side/low-side configuration. High-voltage processing techniques enable the DGD2101's high side to switch to 600V in a bootstrap operation. The 50ns (max) propagation delay matching between the high and the low side drivers allows high frequency switching.

The DGD2101 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high-pulse current buffers designed for minimum driver cross conduction. The low-side gate driver and logic share a common ground.

The DGD2101 is available in a space saving 8-pin SO-8 (Type TH) package, the operating temperature extends from -40°C to +125°C.

Applications

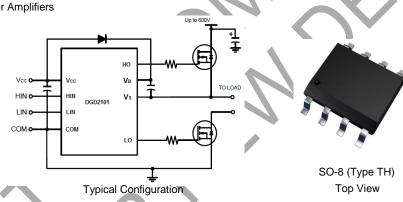
- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers

Features

- Floating High-side Driver in Bootstrap Operation to 600V
- Drives Two N-Channel MOSFETs or IGBTs in High-side / Lowside Configuation
- Outputs Tolerant to Negative Transients
- Wide Low-side Gate Driver and Logic Supply: 10V to 20V
- Logic Inputs CMOS and TTL Compatible (Down to 3.3V)
- Schmitt Triggered Logic Inputs with Internal Pull Down
- Undervoltage Lockout for Vcc
- Space Saving SO-8 (Type TH) Package Available
- Extended Temperature Range: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 🔞
 - SO-8 (Type TH) Weight: 0.075 grams (Approximate)



Ordering Information (Note 4)

Part NumberMarkingReel Size (inches)Tape Width (mm)Quantity Per ReelDGD2101S8-13DGD210113122,500					
DGD2101S8-13 DGD2101 13 12 2,500	Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
	DGD2101S8-13	DGD2101	13	12	2,500

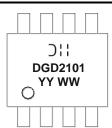
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

and Lead-free

Notes[.]

- 3. Halogen and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

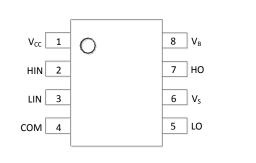


Oll= Manufacturer's MarkingDGD2101 = Product Type Marking CodeYY= Year (ex: 17 = 2017)WW= Week (01 to 53)

DGD2101 Document number: DS38269 Rev. 3 - 3



Pin Diagrams

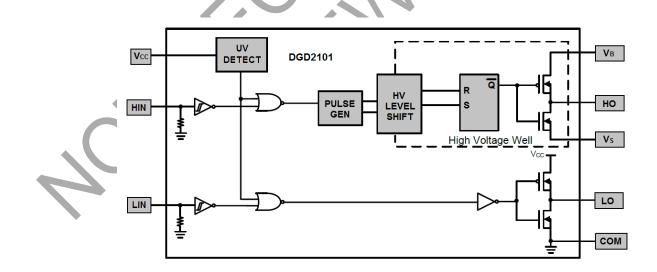


Top View: SO-8 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	Vcc	Low-side and logic fixed supply
2	HIN	Logic input for high-side gate driver output (HO), in phase
3	LIN	Logic input for low-side gate driver output (LO), in phase
4	COM	Low-side return
5	LO	Low-side gate drive output
6	Vs	High-side floating supply return
7	HO	High-side gate drive output
8	VB	High-side floating supply

Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
High-Side Floating Supply Voltage	VB	-0.3 to +624	V	
High-Side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V	
High-Side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V	
Offset Supply Voltage Transient	dVs / dt	50	V/ns	
Low-Side and Logic Fixed Supply Voltage	V _{CC}	-0.3 to +24	V	
Low-Side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V	
Logic Input Voltage (HIN and LIN)	V _{IN}	-0.3 to V _{CC} +0.3	V	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	PD	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	200	°C/W
Thermal Resistance, Junction to Case (Note 5)	R _{θJC}	45	°C/W
Operating Temperature	TJ	+150	°C
Storage Temperature Range	T _{STG}	-55 to +150	C
	1516		<u> </u>

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-Side Floating Supply Absolute Voltage	VB	Vs + 10	Vs + 20	V
High-Side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High-Side Floating Output Voltage	V _{HO}	Vs	VB	V
Low-Side and Logic Fixed Supply Voltage	Vcc	10	20	V
Low-Side Output Voltage	VLO	0	V _{CC}	V
Logic Input Voltage (HIN and LIN)	V _{IN}	0	5	V
Ambient Temperature	T _A	-40	+125	°C

Note: 6. Logic operation for $V_S = -5V$ to +600V.





DC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, @T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" Input Voltage	VIH	2.5	—	_	V	$V_{CC} = 10V$ to 20V
Logic "0" Input Voltage	VIL	—	—	0.8	V	V_{CC} = 10V to 20V
High Level Output Voltage, V _{BIAS} - V _O	V _{OH}	—	0.05	0.2	V	$I_0 = 2mA$
Low Level Output Voltage, V _O	Vol	—	0.02	0.1	V	$I_0 = 2mA$
Offset Supply Leakage Current	I _{LK}	—	_	50	μA	$V_{B} = V_{S} = 600V$
Quiescent V _{BS} Supply Current	I _{BSQ}	—	30	55	μA	$V_{IN} = 0V \text{ or } 5V$
Quiescent V _{CC} Supply Current	lccq	—	150	270	μA	$V_{IN} = 0V \text{ or } 5V$
Logic "1" Input Bias Current	I _{IN+}	—	3.0	10	μA	V _{IN} = 5V
Logic "0" Input Bias Current	I _{IN-}	—	_	5.0	μA	$V_{IN} = 0V$
V _{CC} Supply Undervoltage Positive Going Threshold	V _{CCUV+}	8.0	8.9	9.8	V	-
V _{CC} Supply Undervoltage Negative Going Threshold	V _{CCUV-}	7.4	8.2	9.0	V	—
Output High Short Circuit Pulsed Current	I _{O+}	130	290	$\langle - \rangle$	mA	V _O = 0V, V _{IN} = Logic"1", PW ≤ 10µs
Output Low Short Circuit Pulsed Current	I _{O-}	270	600	$\mathbf{\nabla}$	mA	$V_O = 15V$, $V_{IN} = Logic"0$ ", PW $\leq 10\mu s$

Note: 7. The V_{IN} and I_{IN} parameters are referenced to COM. The V_O and I_O parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, C_L = 1000pF, $@T_A = +25^{\circ}C$, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-on Propagation Delay	ton	-	160	220	ns	$V_S = 0V$
Turn-off Propagation Delay	tOFF	-	150	220	ns	$V_{\rm S} = 600 V$
Turn-on Rise Time	t _R	_	70	170	ns	—
Turn-off Fall Time	t⊨	+	35	90	ns	—
Delay Matching	t _{DM}			50	ns	—





Timing Waveforms

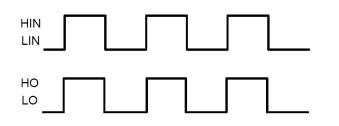


Figure 1. Input / Output Timing Diagram

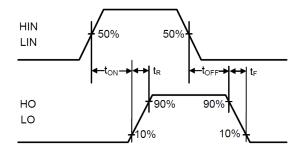


Figure 2. Switching Time Waveform Definitions

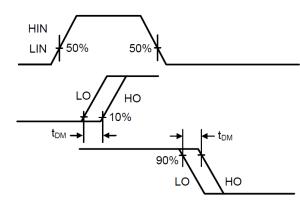


Figure 3. Delay Matching Waveform Definitions



Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

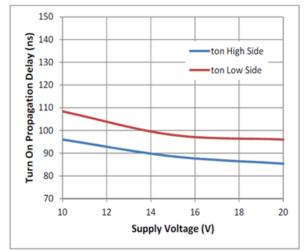
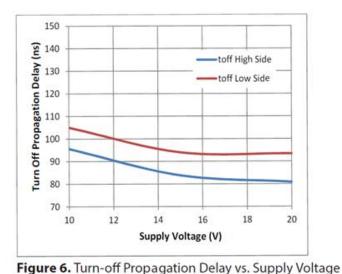


Figure 4. Turn-on Propagation Delay vs. Supply Voltage



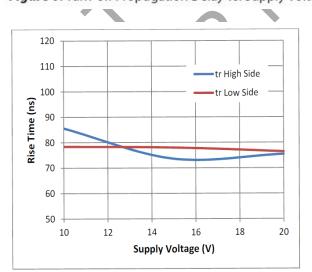
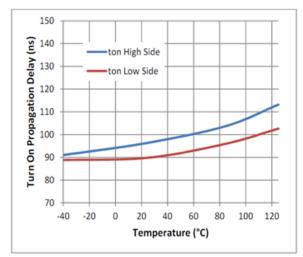
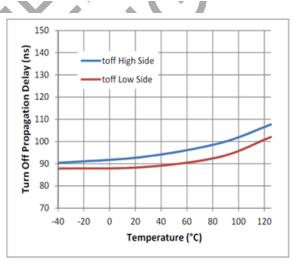


Figure 8. Rise Time vs. Supply Voltage









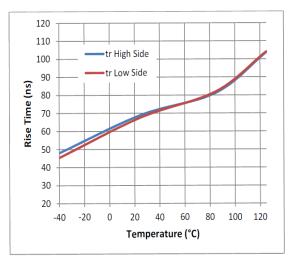


Figure 9. Rise Time vs. Temperature



Typical Performance Characteristics (Cont.)

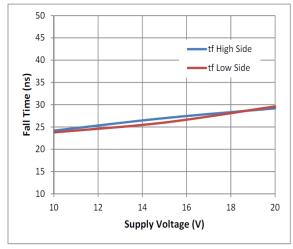
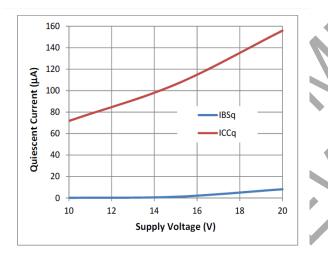
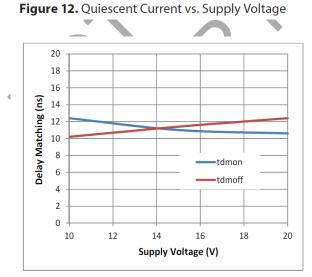


Figure 10. Fall Time vs. Supply Voltage







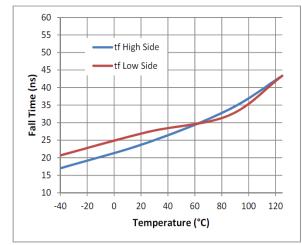


Figure 11. Fall Time vs. Temperature

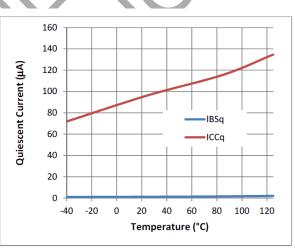


Figure 13. Quiescent Current vs. Temperature

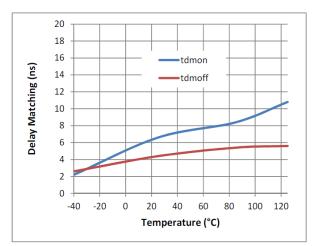
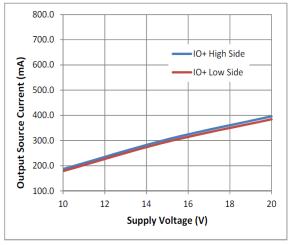


Figure 15. Delay Matching vs. Temperature

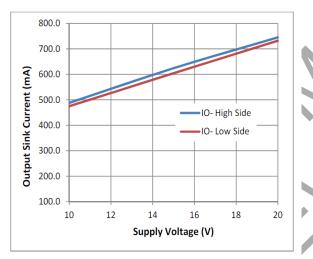


DGD2101

Typical Performance Characteristics (Cont.)









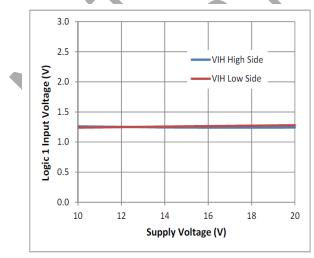


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

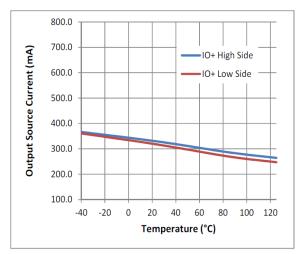


Figure 17. Output Source Current vs. Temperature

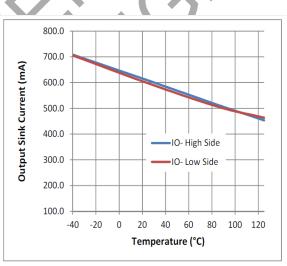


Figure 19. Output Sink Current vs. Temperature

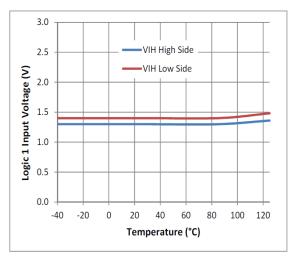


Figure 21. Logic 1 Input Voltage vs. Temperature



Typical Performance Characteristics (Cont.)

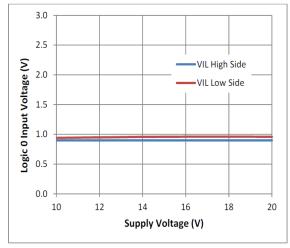
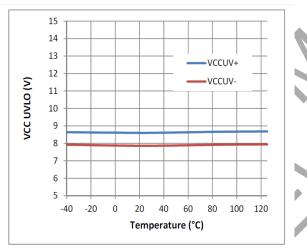
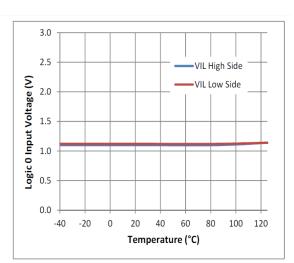


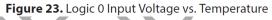
Figure 22. Logic 0 Input Voltage vs. Supply Voltage











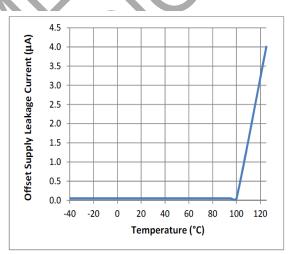


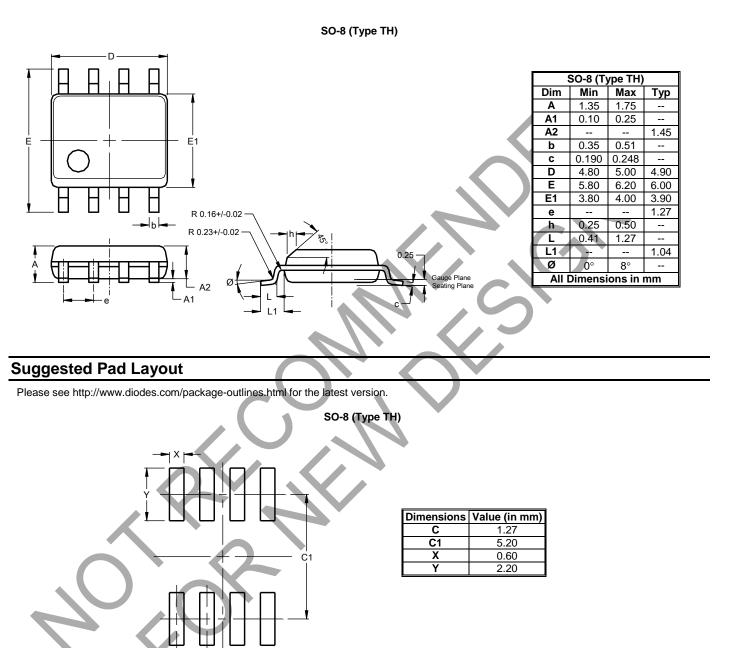
Figure 25. Offset Supply Leakage Current vs. Temperature



DGD2101

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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